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SiW ECAL for future e^+e^- collider

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ABSTRACT: Calorimeters with silicon detectors have many unique features and are proposed for several world-leading experiments. We discuss the tests of the first three 18×18 cm² layers segmented into 1024 pixels of the technological prototype of the silicon-tungsten electromagnetic calorimeter for a future e^+e^- collider. The tests have beem performed in November 2015 at CERN SPS beam line.

KEYWORDS: Calorimeter methods, calorimeters, silicon microstrip and pad detectors.

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1 Silicon calorimeters in ILD and beyond

Silicon detectors without amplification have excellent characteristics not only for tracking devices but also for calorimeters. They are easily segmentable, perfectly linear, independent of environmental changes and stable in time. The response to minimum-ionizing particle (MIP) is determined only by the thickness of p–n junction and the gain of front-end electronics, therefore it is uniform across the channels within a few percent and easy to calibrate. Overall, with the silicon calorimeters one can achieve the best granularity and the lowest systematics, which makes them ideal for a precise electromagnetic calorimetry optimized for Particle Flow Algorithms (PFA) at International Linear Collider (ILC) [1] or other future e^+e^- collider. In addition, the silicon detectors are radiation hard which is of utmost importance for Large Hadron Collider (LHC). They can provide the timing at the level of 20–50 psec which is also important for both LHC and ILC.

The main disadvantage of the silicon detectors is a high cost. For large scale production, like for International Large Detector (ILD) [2], the expected price from Hamamatsu HPK company, Japan is about 2.5 EUR/cm². The silicon calorimeter also requires a low-noise electronics. The intrinsic stochastic energy resolution of the ILD silicon-tungsten electromagnetic calorimeter (SiW ECAL) is $17-20\%/\sqrt{E/\text{GeV}}$ depending on the number of layers and the silicon thickness. This resolution is sufficient for PFA, since the jet energy resolution is dominated by the hadronic calorimeter measurement at low energies (below 100 GeV) and by the shower overlaps causing "confusion" in assigning calorimeter hits to the right particles at high energies.

Silicon ECAL has been proposed for all future e^+e^- collider experiments (ILD, SiD [2], CEPC [3, 4], FCC [5], CLIC [6]). It has been approved by CMS collaboration for the phase-II upgrade of their calorimeter endcaps (High-Granularity CALorimeter, HGCAL [7]). It is planned to install 40 radiation-hard silicon layers in each endcap. Currently, HGCAL collaboration carries out an intensive research on the shower timing at the level of ~20 psec. It should allow to localize the region of a primary interaction and to reduce effectively the CMS phase-II pile-up of 140–200. The same principle is studied by ATLAS. They propose High Granularity Timing Detector (HGTD) [8], a preshower in front of the currently installed liquid argon calorimeter. Here, the smaller signal, either MIP-like or from the very beginning of the shower, is amplified in the silicon by a factor of

~ 10 ("Low Gain Avalanche Detector"). Finally, a few silicon layers with high granularity and fast timing are proposed to be integrated in LHCb ECAL in phase II upgrade [9]. They should help to fight against the pile-up and also to measure better the angle between π^0 photons and in this way to improve its mass resolution.

2 Tests of technological prototype at CERN SPS

This paper describes the recent progress in SiW ECAL R&D for ILD. In 2004–2011 the so-called "physical" prototype of SiW ECAL with 30 layers has been build and successfully tested within CALICE collaboration [10]. It was designed to prove the physical PFA principles in beam tests. The electronics was not embedded inside the calorimeter but put aside.

After the physical prototype, the emphasis has moved to the technological realization of the detector scalable to ILD ECAL. This second generation prototype is called "technological". The electronics is embedded in the active layer. It is based on a dedicated 64 channel front-end chip SKIROC [11]. Each channel has 15 memory slots called SCA digitized by 12 bit Analog-to-Digital-Converter (ADC) linear in the range of about 1–1500 MIPs. SKIROC has auto-trigger capabilities as in ILD there is no central trigger, the event is built using bunch crossing (BX) time stamps.

In the current design, ILC collides bunch trains during 1 msec and then stays idle for 199 msec. The latter period is used to readout the data stored in SKIROC. To save the power and to simplify the cooling, the front-end electronics is switched off after each readout cycle. This is called "power pulsing". In such a mode one SKIROC channel consumes only about 27 μW . In practice, however, the electronics should be switched on before the bunch trains so that the transition processes (causing e.g. pedestal drifts) finish well in advance.

A printed circuit board (PCB) of the current prototype has 16 SKIROC chips and 1024 channels. It serves 4 silicon sensors each segmented into 256 pixels of 5.5×5.5 mm² size. The pixels are glued to the corresponding PCB pads with the conductive epoxy. This gluing technology was proven by several years of tests of the physical prototype.

The technological prototype has already reached the density of channels required for ILD. The next steps will be to connect several such detector elements in-line and on both sides of the absorber layer to form an ILD detector element called "slab".

Two series of technological prototype tests have been performed at CERN SPS, in November 2015 and in June 2016. By the time of the first test 4 layers each with 1024 channels have been built and brought to the beam, 3 of them were successfully operated during the tests. The SPS beam time was kindly provided by CMS HGCAL. The second beam campaign was provided by Semi-Digital HCAL (SDHCAL) [12] and was envisaged as a combined test of high granularity ECAL and HCAL. By that time 10 ECAL layers have been built, 7 were operational but 6 of them suffered from high noises. Only one layer was fully operational. Therefore, in the following we discuss only the SPS tests in November 2015 with 3 layers. The next beam tests with standalone SiW ECAL are planned in June 2017 in DESY, Germany.

2.1 Pedestals

In the current version of SKIROC chip there is no pedestal suppression: every trigger initiates readout of pedestals in all non-triggered channels. This provides a lot of pedestal data which was

useful for the debugging as the determination of the pedestal positions was found to be not so trivial.

First, they should be calculated not only per channel but also per SCA memory slot. With 15 memories for each channel, the total number of pedestals in one layer is $1024 \times 15 = 15360$. Second, there is a small fraction of events where one or more channels trigger on negative signals possibly caused by a pick-up noise from digital lines. The pedestals in other channels are distorted so that such events should be excluded.

Finally, there is one more complication. The triggered event in one bunch crossing (BX) may be followed by several "retriggers" in BX+1, BX+2, BX+3, ... With low trigger threshold or in high noise conditions similar retrigger sequences may appear spontaneously and may even dominate the data stream. This actually happened in June 2016 beam tests in 6 layers, when only one was working properly at the nominal trigger threshold.

In November 2015 the retriggers were acceptable in all 3 readout layers. However, in the events followed by retriggers the pedestals were shifted from the right values. The MIP signal position was not affected, however. The difference between triggered and pedestal data might arise from the fact that the pedestals are recorded with some delay, namely, at the edge of the next bunch clock.

In the end, the pedestals were calculated per channel, per SCA memory in the events without any negative signals and not followed by retriggers. A few problematic channels (#37 in all chips and #45-47 in chips 1,9 with double peak pedestals) are excluded. The resulting pedestal spectra are approximately Gaussian, as shown by red open histogram in Figure 1 left for about 1000 channels in one layer. There is an excellent separation of the pedestals and the MIP signals peaking at \sim 65.



Figure 1. Left: the combined ADC spectra for all channels of one layer during two hours muon run. Triggered and pedestal data are shown separately. A peak at zero for the former is produced by spontaneous retriggers. Right: the ratio of the MIP signal (65 channels) to the pedestal width for various running conditions.

SKIROC gain is regulated by the configurable preamplifier feedback capacitance. For an ILD dynamic range it should be set to the maximal value of 6 pF. It was found, however, that about twice better signal-over-noise ratio can be obtained with five times higher gain corresponding to 1.2 pF. This value was chosen for November 2015 beam tests. The fact that the noise increases less than the gain at 1.2 pF means that the preamplifier noise is not dominating in SKIROC.

Pedestal width reflecting the noises is studied in 19 two-hours muon runs taken in 5 consecutive days. The ratio of the MIP most-probable-value (65 ADC channels) to the standard deviation of the pedestal spectrum per channel, SCA and muon run is shown in Figure 1 right. It summarizes

316 000 pedestal spectra with at least 100 events accumulated in about 3000 channels. Different colors distinguish different running conditions: with 200 msec data taking period and with ECAL perpendicular to the beam ("standard settings") or turned later by about 45°, and with 1.1 msec period to emulate ILC bunch trains ("short spills"). One can see that in average signal-over-noise ratio is about 19, which demonstrates an excellent potential of the SKIROC chip.

The measured pedestal positions stay constant in 18 muon runs with respect to the first one (taken with the "standard settings") with a standard deviation equal to 0.4% of the MIP signal. There is one exception, however, when the first layer was operated with 1.1 msec data taking period its pedestals deviated in average by 3.8% of the MIP. This indicates a pedestal drift continuing beyond currently set 1.4 msec delay after switching on the electronics in power pulsing mode. In other two layers no pedestal drift was observed.

2.2 Muon detection efficiency and gain uniformity

Three ECAL layers are sufficient for an efficiency determination: one layer can be studied when two others are put in coincidence and used as an "offline trigger". 150 GeV muons have been used for this analysis. Since they traversed ECAL almost perpendicularly, for the trigger coincidence the hit pixel position is required to be the same in both layers. For the layer under study this requirement is relaxed so that the fired pixel can deviate by at most one pixel in both coordinates. The time coincidence between the layers is detected if the bunch crossing (BX) clock numbers (with the period of 400 nsec), differ by at most 1. Possible retriggers in BX+1, BX+2, ... following the muon in BX are removed. The pixel is defined to be hit if it has a SKIROC trigger flag set and its pedestal subtracted ADC value exceeds 20 (40 for the trigger). To suppress showers from 150 GeV muons it is required that every trigger layer has only one hit.

There is one more complication: the inefficiency in the central chips with high occupancy could be due to a limited SKIROC memory. To exclude this possibility it is required that the chip whose efficiency is studied, has at least one empty memory slot in the end of data taking.

The resulting inefficiency is mainly due to the SKIROC trigger threshold (230 for this beam test). The probability that the pixel becomes efficient due to a random noise is negligible. For 2.9% of channels the inefficiency is found to be > 20%. This is dominated by one chip in layer 3 (2.1%). The rest is dominated by the inefficiency due to masked pixels in the studied layer but not in the trigger. The efficiency averaged over all channels without 2.9% of outliers per chip is 98–99% and is shown in Figure 2.

The transverse beam spot in the first layer and its muon ADC pedestal subtracted spectrum summed over all channels after requiring the coincidence with other two layers are shown in Figure 3. The plots for the second and the third layers are similar. The fraction of masked channels was 2.2%.

One of the big advantages of the silicon detector is the gain uniformity across the pixels. This makes the calibration much easier and reduces the systematics. The spread of the muon dE/dx most-probable-value across the pixels before any calibration is measured to be 6.4%. The most-probable-value was calculated for simplicity as the truncated mean among 57% of the lowest pedestal subtracted ADC values in the region above 40. It was required that 100% corresponds to at least 50 events, therefore due to a limited muon statistics at the corners, only 83% of all channels were calibrated in this way.



Figure 2. The efficiency averaged per chip excluding 2.9% of outliers.



Figure 3. Left: first layer muon occupancy plot; right: 150 GeV triggered muon dE/dx energy deposition.

2.3 "Square" events

There is a special electrode at the silicon sensor periphery, called "guard ring'. It smooths the electric field at the edge and ensures low dark currents. Due to technological reasons, in the current technological prototype the guard ring potential is not fixed but floating. Therefore, a big energy deposition there may fire many peripheral pixels via the capacitive coupling and produce "square"-like events. They have been observed in SiW ECAL physical prototype. Contrary to the sensors of the physical prototype, in the technological prototype their guard ring is segmented. This greatly reduces the capacitive coupling.

The probability of "square" events was studied in the showers created by positrons of maximal energy of 100 and 150 GeV traversing 8.4 radiation lengths of the tungsten absorber in front of 3 ECAL layers. 100 GeV positrons were shooting approximately at their centers, i.e. at four corners of the silicon sensors. Therefore, the probability of the "square" events was maximized. 150 GeV beam was shifted horizontally by 1 cm. About 90% of the transverse energy barycenters were contained in an ellipsoid with 3 cm horizontal and 2 cm vertical axes. In these conditions at 150 GeV (100 GeV) we observed 18 (69) "square"-like patterns in one of 4 sensors out of 119 000 (390 000) events, which corresponds to the probability of $4 \cdot 10^{-5}$ per sensor in both data samples.

3 Conclusions

The silicon detectors started to "expand" from the trackers to the calorimeters in world-leading accelerator detectors.

The SiW ECAL technological prototype has reached the ILD design density of channels and has demonstrated the ability to work in ILD "power pulsing" mode. It has MIP-to-noise ratio of ~19 (with the optimal SKIROC gain, 5 times larger than in ILD), the muon efficiency of 98–99% and the spread of the MIP signals of 6.4% measured in 3000 channels before any calibration. With the improved design of the sensor guard rings the probability of "square" events per sensor is measured to be well below 10^{-4} . There is still a lot of work ahead, in particular, on improving the trigger noises.

Acknowledgments

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